

**B. AMENDMENTS TO THE CLAIMS**

1. (currently amended) A semiconductor device, comprising:  
a first resin package comprising:  
a semiconductor chip;  
a chip electrode on a surface of said semiconductor chip;  
a first resin sealing said semiconductor chip; and  
a first package electrode on a surface of said first resin; being electrically connected to said chip electrode, said first package electrode comprising a mounting pad  
~~first electrode region connected to said chip electrode~~ and a testing pad provided apart  
from said mounting pad and said testing pad being in contact with a testing probe to  
enable electrical measurement of said semiconductor chip ~~second electrode region~~  
~~connected to said first electrode region~~; and  
a mounted object connected to said ~~first electrode region~~ mounting pad.
2. (currently amended) The semiconductor device as claimed in claim 1, further comprising:  
a wiring connecting said ~~first electrode region~~ mounting pad to said mounted object.
3. (currently amended) The semiconductor device as claimed in claim 2, wherein  
said ~~first electrode region~~ mounting pad is arranged along an edge of said first resin package, and

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wherein said ~~second electrode region~~ testing pad is arranged at an inner position with respect to said ~~first electrode region~~ mounting pad.

4. (original) The semiconductor device as claimed in claim 3, further comprising:  
a second resin sealing said first resin package and a first surface of said mounted object.

5. (currently amended) The semiconductor device as claimed in claim 4, further comprising:

an inner wiring connecting said chip electrode to said ~~first electrode region~~ mounting pad.

6-12. (withdrawn)

13. (original) The semiconductor device as claimed in claim 1, wherein said mounted object is a mounting substrate.

14-20. (withdrawn)